Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	55MHz
Connectivity	EBI/EMI, I²C, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	88
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 1.95V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-LQFP (20x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at91sam7se256b-aur

Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Comments
PIO				
PA0 - PA31	Parallel IO Controller A	I/O		Pulled-up input at reset
PB0 - PB31	Parallel IO Controller B	I/O		Pulled-up input at reset
PC0 - PC23	Parallel IO Controller C	I/O		Pulled-up input at reset
USB Device Port				
DDM	USB Device Port Data -	Analog		
DDP	USB Device Port Data +	Analog		
USART				
SCK0 - SCK1	Serial Clock	I/O		
TXD0 - TXD1	Transmit Data	I/O		
RXD0 - RXD1	Receive Data	Input		
RTS0 - RTS1	Request To Send	Output		
CTS0 - CTS1	Clear To Send	Input		
DCD1	Data Carrier Detect	Input		
DTR1	Data Terminal Ready	Output		
DSR1	Data Set Ready	Input		
RI1	Ring Indicator	Input		
Synchronous Serial Controller				
TD	Transmit Data	Output		
RD	Receive Data	Input		
TK	Transmit Clock	I/O		
RK	Receive Clock	I/O		
TF	Transmit Frame Sync	I/O		
RF	Receive Frame Sync	I/O		
Timer/Counter				
TCLK0 - TCLK2	External Clock Inputs	Input		
TIOA0 - TIOA2	Timer Counter I/O Line A	I/O		
TIOB0 - TIOB2	Timer Counter I/O Line B	I/O		
PWM Controller				
PWM0 - PWM3	PWM Channels	Output		
Serial Peripheral Interface				
MISO	Master In Slave Out	I/O		
MOSI	Master Out Slave In	I/O		
SPCK	SPI Serial Clock	I/O		
NPCS0	SPI Peripheral Chip Select 0	I/O	Low	
NPCS1-NPCS3	SPI Peripheral Chip Select 1 to 3	Output	Low	

Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Comments
EBI for NAND Flash Support				
NANDCS	NAND Flash Chip Select Line	Output	Low	
NANDOE	NAND Flash Output Enable	Output	Low	
NANDWE	NAND Flash Write Enable	Output	Low	
NANDCLE	NAND Flash Command Line Enable	Output	Low	
NANDALE	NAND Flash Address Line Enable	Output	Low	
SDRAM Controller				
SDCK	SDRAM Clock	Output		Tied low after reset
SDCKE	SDRAM Clock Enable	Output	High	
SDCS	SDRAM Controller Chip Select Line	Output	Low	
BA[1:0]	Bank Select	Output		
SDWE	SDRAM Write Enable	Output	Low	
RAS - CAS	Row and Column Signal	Output	Low	
NBS[3:0]	Byte Mask Signals	Output	Low	
SDA10	SDRAM Address 10 Line	Output		

Note: 1. Refer to Section 6. “/O Lines Considerations” on page 15.

4.2 128-lead LQFP Pinout

Table 4-1. Pinout in 128-lead LQFP Package

1	ADVREF	33	PB31	65	TDI	97	SDCK
2	GND	34	PB30	66	TDO	98	PC8
3	AD7	35	PB29	67	PB2	99	PC7
4	AD6	36	PB28	68	PB1	100	PC6
5	AD5	37	PB27	69	PB0	101	PC5
6	AD4	38	PB26	70	GND	102	PC4
7	VDDOUT	39	PB25	71	VDDIO	103	PC3
8	VDDIN	40	PB24	72	VDDCORE	104	PC2
9	PA20/PGMD8/AD3	41	PB23	73	NRST	105	PC1
10	PA19/PGMD7/AD2	42	PB22	74	TST	106	PC0
11	PA18/PGMD6/AD1	43	PB21	75	ERASE	107	PA31
12	PA17/PGMD5/AD0	44	PB20	76	TCK	108	PA30
13	PA16/PGMD4	45	GND	77	TMS	109	PA29
14	PA15/PGMD3	46	VDDIO	78	JTAGSEL	110	PA28
15	PA14/PGMD2	47	VDDCORE	79	PC23	111	PA27/PGMD15
16	PA13/PGMD1	48	PB19	80	PC22	112	PA26/PGMD14
17	PA12/PGMD0	49	PB18	81	PC21	113	PA25/PGMD13
18	PA11/PGMM3	50	PB17	82	PC20	114	PA24/PGMD12
19	PA10/PGMM2	51	PB16	83	PC19	115	PA23/PGMD11
20	PA9/PGMM1	52	PB15	84	PC18	116	PA22/PGMD10
21	VDDIO	53	PB14	85	PC17	117	PA21/PGMD9
22	GND	54	PB13	86	PC16	118	VDDCORE
23	VDDCORE	55	PB12	87	PC15	119	GND
24	PA8/PGMM0	56	PB11	88	PC14	120	VDDIO
25	PA7/PGMNVALID	57	PB10	89	PC13	121	DM
26	PA6/PGMNOE	58	PB9	90	PC12	122	DP
27	PA5/PGMRDY	59	PB8	91	PC11	123	VDDFLASH
28	PA4/PGMNCMD	60	PB7	92	PC10	124	GND
29	PA3	61	PB6	93	PC9	125	XIN/PGMCK
30	PA2/PGMEN2	62	PB5	94	GND	126	XOUT
31	PA1/PGMEN1	63	PB4	95	VDDIO	127	PLLRC
32	PA0/PGMEN0	64	PB3	96	VDDCORE	128	VDDPLL

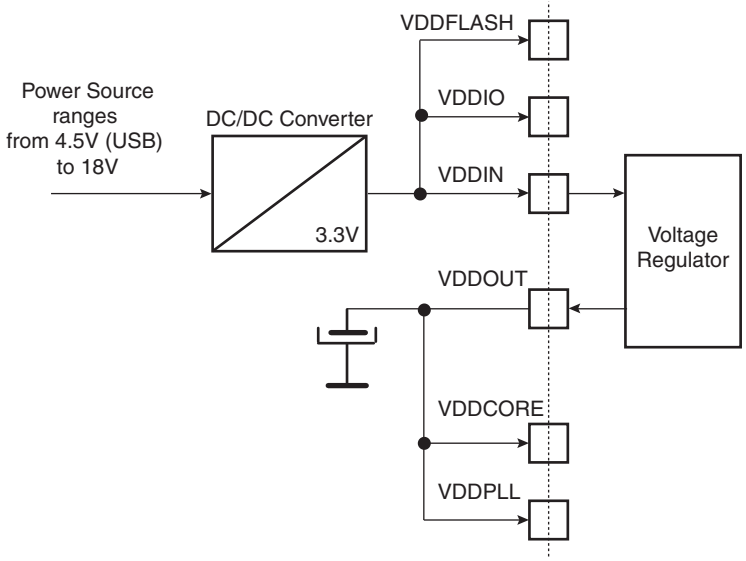
- One external 2.2 µF (or 3.3 µF) X7R capacitor should be connected between VDDOUT and GND.

Adequate input supply decoupling is mandatory for VDDIN in order to improve startup stability and reduce source voltage drop. The input decoupling capacitor should be placed close to the chip. For example, two capacitors can be used in parallel: 100 nF NPO and 4.7 µF X7R.

5.4 Typical Powering Schematics

The SAM7SE512/256/32 supports a 3.3V single supply mode. The internal regulator input connected to the 3.3V source and its output feeds VDDCORE and the VDDPLL. Figure 5-1 shows the power schematics to be used for USB bus-powered systems.

Figure 5-1. 3.3V System Single Power Supply Schematic



6. /O Lines Considerations

6.1 JTAG Port Pins

TMS, TDI and TCK are Schmitt trigger inputs. TMS, TDI and TCK do not integrate a pull-up resistor.

TDO is an output, driven at up to VDDIO, and has no pull-up resistor.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. The JTAGSEL pin integrates a permanent pull-down resistor of about 15 kΩ.

To eliminate any risk of spuriously entering the JTAG boundary scan mode due to noise on JTAGSEL, it should be tied externally to GND if boundary scan is not used, or put in place an external low value resistor (such as 1 kΩ).

6.2 Test Pin

The TST pin is used for manufacturing test or fast programming mode of the SAM7SE512/256/32 when asserted high. The TST pin integrates a permanent pull-down resistor of about 15 kΩ to GND.

To eliminate any risk of entering the test mode due to noise on the TST pin, it should be tied to GND if the FFPI is not used, or put in place an external low value resistor (such as 1 kΩ).

To enter fast programming mode, the TST pin and the PA0 and PA1 pins should be tied high and PA2 tied low.

Driving the TST pin at a high level while PA0 or PA1 is driven at 0 leads to unpredictable results.

6.3 Reset Pin

The NRST pin is bidirectional with an open-drain output buffer. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. There is no constraint on the length of the reset pulse, and the reset controller can guarantee a minimum pulse length. This allows connection of a simple push-button on the NRST pin as system user reset, and the use of the NRST signal to reset all the components of the system.

An external power-on reset can drive this pin during the start-up instead of using the internal power-on reset circuit.

The NRST pin integrates a permanent pull-up of about 100 kΩ resistor to VDDIO.

This pin has Schmitt trigger input.

6.4 ERASE Pin

The ERASE pin is used to re-initialize the Flash content and some of its NVM bits. It integrates a permanent pull-down resistor of about 15 kΩ to GND.

To eliminate any risk of erasing the Flash due to noise on the ERASE pin, it should be tied externally to GND, which prevents erasing the Flash from the application, or put in place an external low value resistor (such as 1 kΩ).

This pin is debounced by the RC oscillator to improve the glitch tolerance. When the pin is tied to high during less than 100 ms, ERASE pin is not taken into account. The pin must be tied high during more than 220 ms to perform the re-initialization of the Flash.

7. Processor and Architecture

7.1 ARM7TDMI Processor

- RISC processor based on ARMv4T Von Neumann architecture
  - Runs at up to 55 MHz, providing 0.9 MIPS/MHz (core supplied with 1.8V)
- Two instruction sets
  - ARM® high-performance 32-bit instruction set
  - Thumb® high code density 16-bit instruction set
- Three-stage pipeline architecture
  - Instruction Fetch (F)
  - Instruction Decode (D)
  - Execute (E)

7.2 Debug and Test Features

- EmbeddedICE™ (Integrated embedded in-circuit emulator)
  - Two watchpoint units
  - Test access port accessible through a JTAG protocol
  - Debug communication channel
- Debug Unit
  - Two-pin UART
  - Debug communication channel interrupt handling
  - Chip ID Register
- IEEE1149.1 JTAG Boundary-scan on all digital pins

7.3 Memory Controller

- Programmable Bus Arbiter
  - Handles requests from the ARM7TDMI and the Peripheral DMA Controller
- Address decoder provides selection signals for
  - Four internal 1 Mbyte memory areas
  - One 256-Mbyte embedded peripheral area
  - Eight external 256-Mbyte memory areas
- Abort Status Registers
  - Source, Type and all parameters of the access leading to an abort are saved
  - Facilitates debug by detection of bad pointers
- Misalignment Detector
  - Alignment checking of all data accesses
  - Abort generation in case of misalignment
- Remap Command
  - Remaps the SRAM in place of the embedded non-volatile memory
  - Allows handling of dynamic exception vectors
- 16-area Memory Protection Unit (Internal Memory and peripheral protection only)

  - Individually programmable size between 1K Byte and 1M Byte
  - Individually programmable protection against write and/or user access
  - Peripheral protection against write and/or user access
- Embedded Flash Controller
  - Embedded Flash interface, up to three programmable wait states
  - Prefetch buffer, buffering and anticipating the 16-bit requests, reducing the required wait states
  - Key-protected program, erase and lock/unlock sequencer
  - Single command for erasing, programming and locking operations
  - Interrupt generation in case of forbidden operation

7.4 External Bus Interface

- Integrates Three External Memory Controllers:
  - Static Memory Controller
  - SDRAM Controller
  - ECC Controller
- Additional Logic for NAND Flash and CompactFlash® Support
  - NAND Flash support: 8-bit as well as 16-bit devices are supported
  - CompactFlash support: all modes (Attribute Memory, Common Memory, I/O, True IDE) are supported but the signals _IOIS16 (I/O and True IDE modes) and -ATA SEL (True IDE mode) are not handled.
- Optimized External Bus:
  - 16- or 32-bit Data Bus (32-bit Data Bus for SDRAM only)
  - Up to 23-bit Address Bus, Up to 8-Mbytes Addressable
  - Up to 8 Chip Selects, each reserved to one of the eight Memory Areas
  - Optimized pin multiplexing to reduce latencies on External Memories
- Configurable Chip Select Assignment:
  - Static Memory Controller on NCS0
  - SDRAM Controller or Static Memory Controller on NCS1
  - Static Memory Controller on NCS2, Optional CompactFlash Support
  - Static Memory Controller on NCS3, NCS5 - NCS6, Optional NAND Flash Support
  - Static Memory Controller on NCS4, Optional CompactFlash Support
  - Static Memory Controller on NCS7

7.5 Static Memory Controller

- External memory mapping, 512-Mbyte address space
- 8-, or 16-bit Data Bus
- Up to 8 Chip Select Lines
- Multiple Access Modes supported
  - Byte Write or Byte Select Lines
  - Two different Read Protocols for each Memory Bank

- Multiple device adaptability
  - Compliant with LCD Module
  - Compliant with PSRAM in synchronous operations
  - Programmable Setup Time Read/Write
  - Programmable Hold Time Read/Write
- Multiple Wait State Management
  - Programmable Wait State Generation
  - External Wait Request
  - Programmable Data Float Time

7.6 SDRAM Controller

- Numerous configurations supported
  - **2K, 4K, 8K Row Address Memory Parts**
  - **SDRAM with two or four Internal Banks**
  - **SDRAM with 16- or 32-bit Data Path**
- Programming facilities
  - **Word, half-word, byte access**
  - **Automatic page break when Memory Boundary has been reached**
  - **Multibank Ping-pong Access**
  - **Timing parameters specified by software**
  - **Automatic refresh operation, refresh rate is programmable**
- **Energy-saving capabilities**
  - **Self-refresh, and Low-power Modes supported**
- Error detection
  - **Refresh Error Interrupt**
- **SDRAM Power-up Initialization by software**
- **Latency is set to two clocks (CAS Latency of 1, 3 Not Supported)**
- **Auto Precharge Command not used**
- Mobile SDRAM supported (except for low-power extended mode and deep power-down mode)

7.7 Error Corrected Code Controller

- Tracking the accesses to a NAND Flash device by triggering on the corresponding chip select
- Single bit error correction and 2-bit Random detection.
- Automatic Hamming Code Calculation while writing
  - ECC value available in a register
- Automatic Hamming Code Calculation while reading
  - Error Report, including error flag, correctable error flag and word address being detected erroneous
  - Supports 8- or 16-bit NAND Flash devices with 512-, 1024-, 2048- or 4096-byte pages

Figure 8-1. SAM7SE Memory Mapping

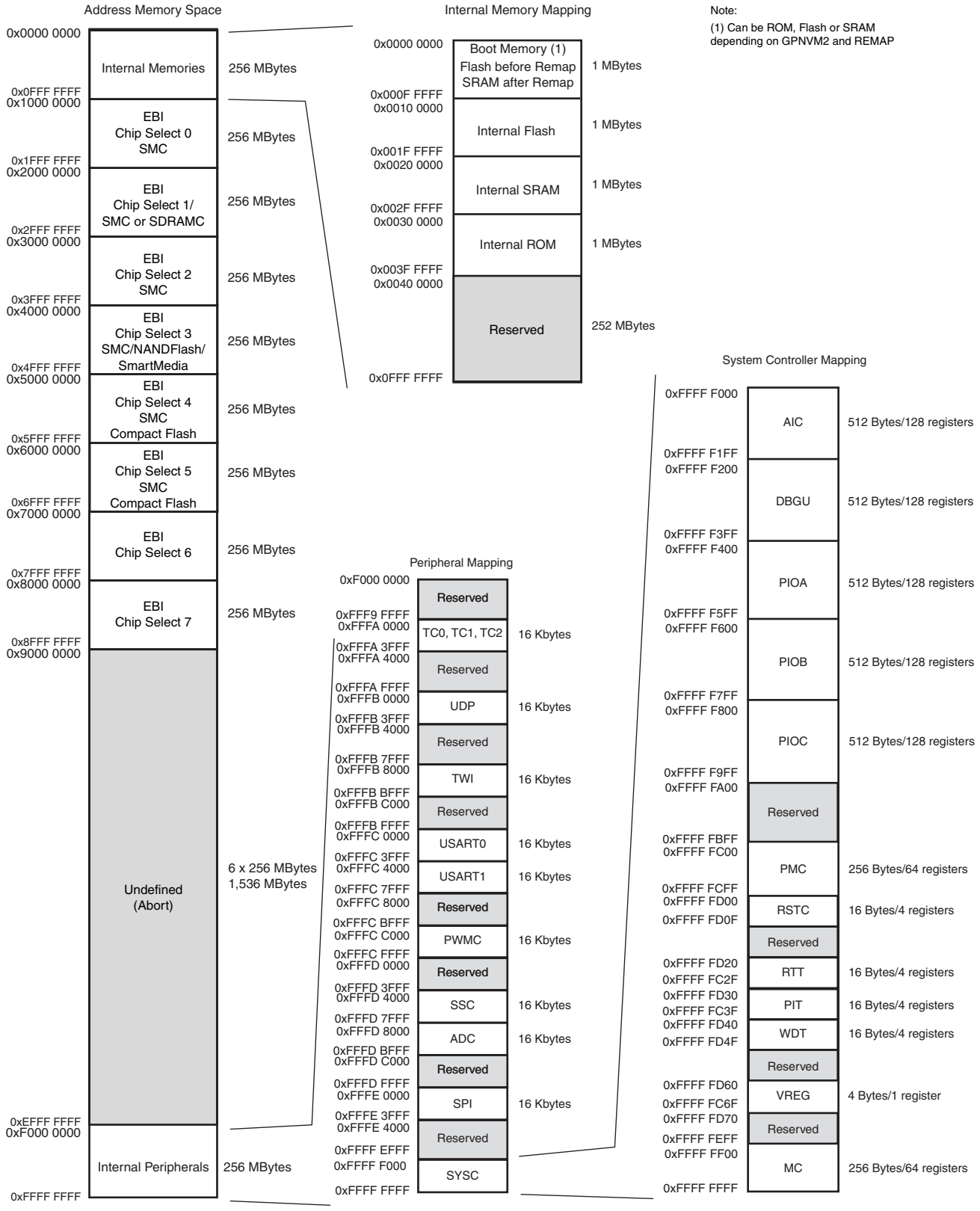


Figure 8-2. Internal Memory Mapping with GPNVM Bit 2 = 0 (default)

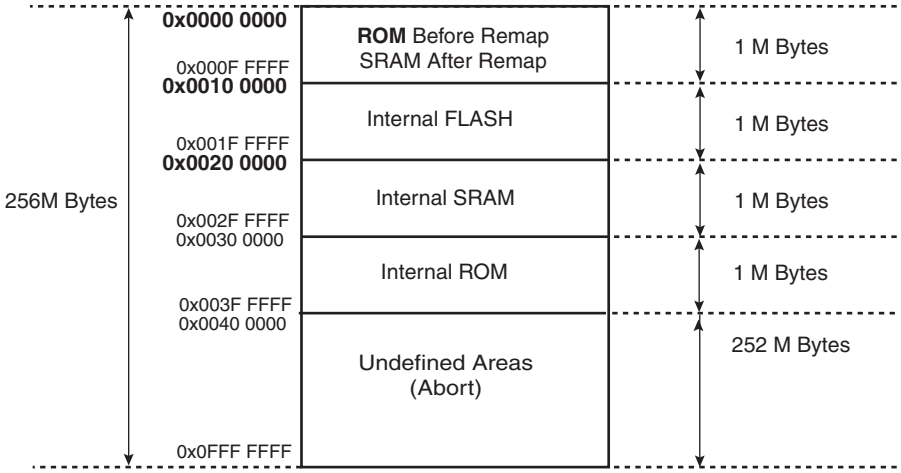
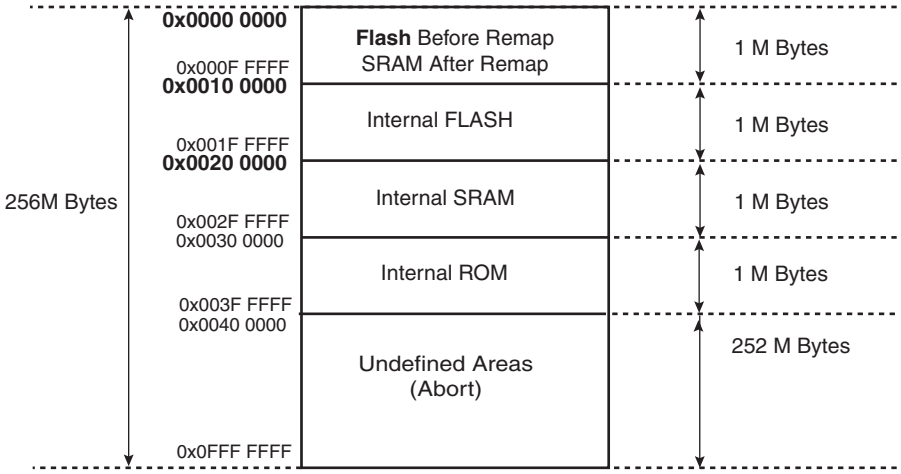


Figure 8-3. Internal Memory Mapping with GPNVM Bit 2 = 1



8.1.2 Embedded Flash

8.1.2.1 Flash Overview

The Flash of the SAM7SE512 is organized in two banks (dual plane) of 1024 pages of 256 bytes. It reads as 131,072 32-bit words.

The Flash of the SAM7SE256 is organized in 1024 pages (single plane) of 256 bytes. It reads as 65,536 32-bit words.

The Flash of the SAM7SE32 is organized in 256 pages (single plane) of 128 bytes. It reads as 8192 32-bit words.

The Flash of the SAM7SE32 contains a 128-byte write buffer, accessible through a 32-bit interface.

The Flash of the SAM7SE512/256 contains a 256-byte write buffer, accessible through a 32-bit interface.

The Flash benefits from the integration of a power reset cell and from the brownout detector. This prevents code corruption during power supply changes, even in the worst conditions.

8.1.2.2 *Embedded Flash Controller*

The Embedded Flash Controller (EFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped within the Memory Controller on the APB. The User Interface allows:

- programming of the access parameters of the Flash (number of wait states, timings, etc.)
- starting commands such as full erase, page erase, page program, NVM bit set, NVM bit clear, etc.
- getting the end status of the last command
- getting error status
- programming interrupts on the end of the last commands or on errors

The Embedded Flash Controller also provides a dual 32-bit Prefetch Buffer that optimizes 16-bit access to the Flash. This is particularly efficient when the processor is running in Thumb mode.

- Two EFCs (EFC0 and EFC1) are embedded in the SAM7SE512 to control each plane of 256 KBytes. Dual plane organization allows concurrent Read and Program.
- One EFC (EFC0) is embedded in the SAM7SE256 to control the single plane 256 KBytes.
- One EFC (EFC0) is embedded in the SAM7SE32 to control the single plane 32 KBytes.

8.1.2.3 *Lock Regions*

The SAM7SE512 Embedded Flash Controller manages 32 lock bits to protect 32 regions of the flash against inadvertent flash erasing or programming commands. The SAM7SE512 contains 32 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

The SAM7SE256 Embedded Flash Controller manages 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The SAM7SE256 contains 16 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

The SAM7SE32 Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The SAM7SE32 contains 8 lock regions and each lock region contains 32 pages of 128 bytes. Each lock region has a size of 4 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the EFC triggers an interrupt.

The 32 (SAM7SE512), 16 (SAM7SE256) or 8 (SAM7SE32) NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.1.2.4 *Security Bit Feature*

The SAM7SE512/256/32 features a security bit, based on a specific NVM-bit. When the security is enabled, any access to the Flash, either through the ICE interface or through the Fast Flash Programming Interface, is forbidden.

8.1.4 SAM-BA® Boot

The SAM-BA Boot is a default Boot Program which provides an easy way to program in-situ the on-chip Flash memory.

The SAM-BA Boot Assistant supports serial communication via the DBGU or the USB Device Port.

- Communication via the DBGU supports a wide range of crystals from 3 to 20 MHz via software auto-detection.
- Communication via the USB Device Port is limited to an 18.432 MHz crystal.

The SAM-BA Boot provides an interface with SAM-BA Graphic User Interface (GUI).

The SAM-BA Boot is in ROM and is mapped in Flash at address 0x0 when GPNVM bit 2 is set to 0.

8.2 External Memories

The external memories are accessed through the External Bus Interface.

Refer to the memory map in Figure 8-1 on page 22.

9. System Controller

The System Controller manages all vital blocks of the microcontroller: interrupts, clocks, power, time, debug and reset.

The System Controller peripherals are all mapped to the highest 4 Kbytes of address space, between addresses 0xFFFF F000 and 0xFFFF FFFF.

Figure 9-1 on page 29 shows the System Controller Block Diagram.

Figure 8-1 on page 22 shows the mapping of the User Interface of the System Controller peripherals. Note that the Memory Controller configuration user interface is also mapped within this address space.

9.1 Reset Controller

- Based on one power-on reset cell and a double brownout detector
- Status of the last reset, either Power-up Reset, Software Reset, User Reset, Watchdog Reset, Brownout Reset
- Controls the internal resets and the NRST pin output
- Allows to shape a signal on the NRST line, guaranteeing that the length of the pulse meets any requirement.

9.1.1 Brownout Detector and Power On Reset

The SAM7SE512/256/32 embeds one brownout detection circuit and a power-on reset cell. The power-on reset is supplied with and monitors VDDCORE.

Both signals are provided to the Flash to prevent any code corruption during power-up or power-down sequences or if brownouts occur on the VDDCORE power supply.

The power-on reset cell has a limited-accuracy threshold at around 1.5V. Its output remains low during power-up until VDDCORE goes over this voltage level. This signal goes to the reset controller and allows a full re-initialization of the device.

The brownout detector monitors the VDDCORE and VDDFLASH levels during operation by comparing it to a fixed trigger level. It secures system operations in the most difficult environments and prevents code corruption in case of brownout on the VDDCORE or VDDFLASH.

When the brownout detector is enabled and VDDCORE decreases to a value below the trigger level (Vbot18-, defined as Vbot18 - hyst/2), the brownout output is immediately activated.

When VDDCORE increases above the trigger level (Vbot18+, defined as Vbot18 + hyst/2), the reset is released. The brownout detector only detects a drop if the voltage on VDDCORE stays below the threshold voltage for longer than about 1µs.

The VDDCORE threshold voltage has a hysteresis of about 50 mV, to ensure spike free brownout detection. The typical value of the brownout detector threshold is 1.68V with an accuracy of ± 2% and is factory calibrated.

When the brownout detector is enabled and VDDFLASH decreases to a value below the trigger level (Vbot33-, defined as Vbot33 - hyst/2), the brownout output is immediately activated.

When VDDFLASH increases above the trigger level (Vbot33+, defined as Vbot33 + hyst/2), the reset is released. The brownout detector only detects a drop if the voltage on VDDCORE stays below the threshold voltage for longer than about 1µs.

The VDDFLASH threshold voltage has a hysteresis of about 50 mV, to ensure spike free brownout detection. The typical value of the brownout detector threshold is 2.80V with an accuracy of ± 3.5% and is factory calibrated.

The brownout detector is low-power, as it consumes less than 20 µA static current. However, it can be deactivated to save its static current. In this case, it consumes less than 1µA. The deactivation is configured through the GPNVM bit 0 of the Flash.

9.2 Clock Generator

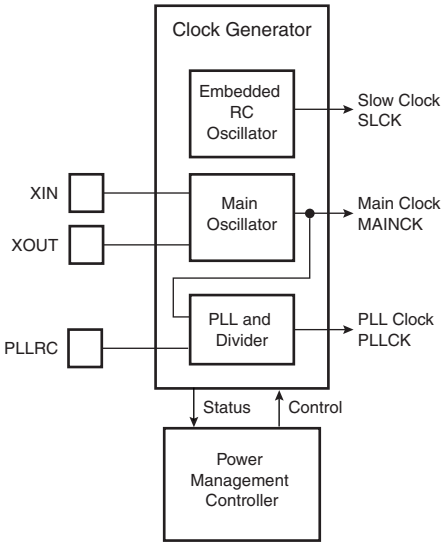
The Clock Generator embeds one low-power RC Oscillator, one Main Oscillator and one PLL with the following characteristics:

- RC Oscillator ranges between 22 KHz and 42 KHz

- Main Oscillator frequency ranges between 3 and 20 MHz
- Main Oscillator can be bypassed
- PLL output ranges between 80 and 220 MHz

It provides SLCK, MAINCK and PLLCK.

Figure 9-2. Clock Generator Block Diagram



9.3 Power Management Controller

The Power Management Controller uses the Clock Generator outputs to provide:

- the Processor Clock PCK
- the Master Clock MCK
- the USB Clock UDPCK
- all the peripheral clocks, independently controllable
- three programmable clock outputs

The Master Clock (MCK) is programmable from a few hundred Hz to the maximum operating frequency of the device.

The Processor Clock (PCK) switches off when entering processor idle mode, thus allowing reduced power consumption while waiting for an interrupt.

9.5 Debug Unit

- Comprises:
  - One two-pin UART
  - One Interface for the Debug Communication Channel (DCC) support
  - One set of Chip ID Registers
  - One Interface providing ICE Access Prevention
- Two-pin UART
  - USART-compatible User Interface
  - Programmable Baud Rate Generator
  - Parity, Framing and Overrun Error
  - Automatic Echo, Local Loopback and Remote Loopback Channel Modes
- Debug Communication Channel Support
  - Offers visibility of COMMRX and COMMTX signals from the ARM Processor
- Chip ID Registers
  - Identification of the device revision, sizes of the embedded memories, set of peripherals
  - Chip ID is 0x272A 0A40 (VERSION 0) for SAM7SE512
  - Chip ID is 0x272A 0940 (VERSION 0) for SAM7SE256
  - Chip ID is 0x2728 0340 (VERSION 0) for SAM7SE32

9.6 Periodic Interval Timer

- 20-bit programmable counter plus 12-bit interval counter

9.7 Watchdog Timer

- 12-bit key-protected Programmable Counter running on prescaled SLCK
- Provides reset or interrupt signals to the system
- Counter may be stopped while the processor is in debug state or in idle mode

9.8 Real-time Timer

- 32-bit free-running counter with alarm running on prescaled SLCK
- Programmable 16-bit prescaler for SLCK accuracy compensation

9.9 PIO Controllers

- Three PIO Controllers. PIO A and B each control 32 I/O lines and PIO C controls 24 I/O lines.
- Fully programmable through set/clear registers
- Multiplexing of two peripheral functions per I/O line
- For each I/O line (whether assigned to a peripheral or used as general-purpose I/O)
  - Input change interrupt
  - Half a clock period glitch filter
  - Multi-drive option enables driving in open drain
  - Programmable pull-up on each I/O line
  - Pin data status register, supplies visibility of the level on the pin at any time

10.3 Peripheral Multiplexing on PIO Lines

The SAM7SE512/256/32 features three PIO controllers, PIOA, PIOB and PIOC, that multiplex the I/O lines of the peripheral set.

PIO Controller A and B control 32 lines; PIO Controller C controls 24 lines. Each line can be assigned to one of two peripheral functions, A or B. Some of them can also be multiplexed with the analog inputs of the ADC Controller.

Table 10-2 on page 37 defines how the I/O lines of the peripherals A and B or the analog inputs are multiplexed on the PIO Controller A, B and C. The two columns “Function” and “Comments” have been inserted for the user’s own comments; they may be used to track how pins are defined in an application.

Note that some peripheral functions that are output only may be duplicated in the table.

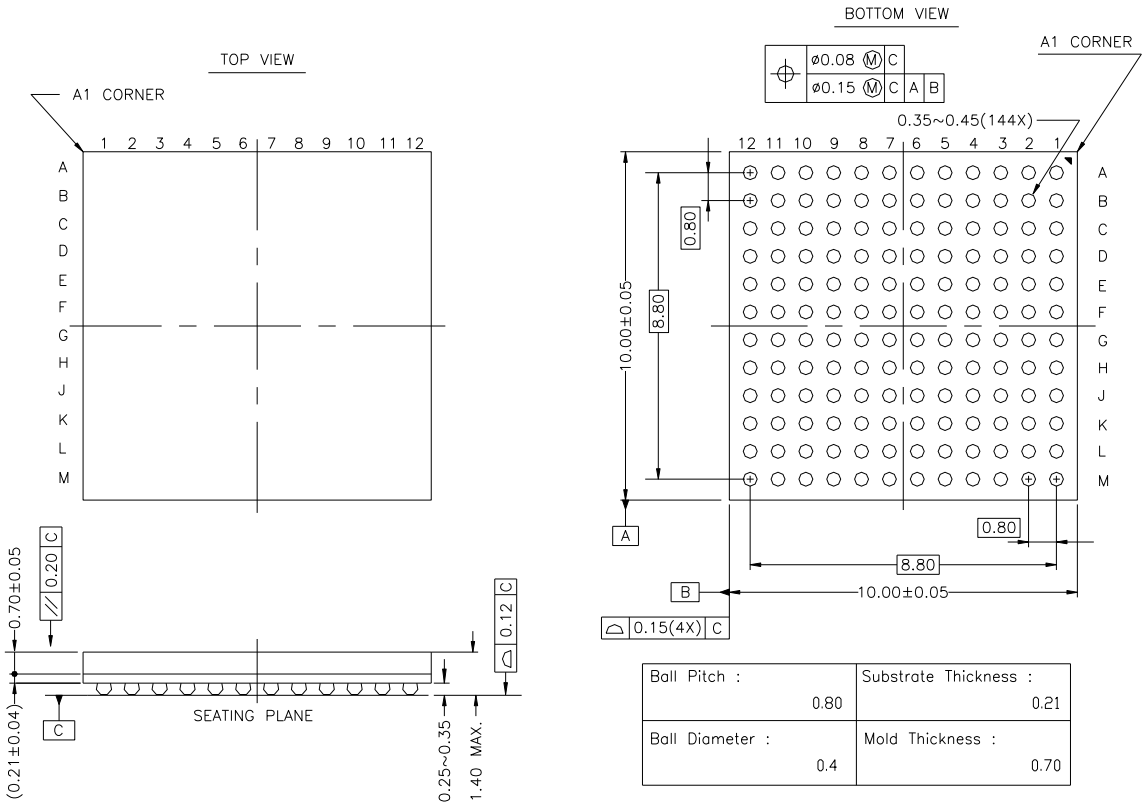
At reset, all I/O lines are automatically configured as input with the programmable pull-up enabled, so that the device is maintained in a static state as soon as a reset is detected.

10.4 PIO Controller A Multiplexing

Table 10-2. Multiplexing on PIO Controller A

PIO Controller A				Application Usage	
I/O Line	**Peripheral A**	**Peripheral B**	**Comments**	**Function**	**Comments**
PA0	PWM0	A0/NBS0	High-Drive		
PA1	PWM1	A1/NBS2	High-Drive		
PA2	PWM2	A2	High-Drive		
PA3	TWD	A3	High-Drive		
PA4	TWCK	A4			
PA5	RXD0	A5			
PA6	TXD0	A6			
PA7	RTS0	A7			
PA8	CTS0	A8			
PA9	DRXD	A9			
PA10	DTXD	A10			
PA11	NPCS0	A11			
PA12	MISO	A12			
PA13	MOSI	A13			
PA14	SPCK	A14			
PA15	TF	A15			
PA16	TK	A16/BA0			
PA17	TD	A17/BA1	AD0		
PA18	RD	NBS3/CFIOW	AD1		
PA19	RK	NCS4/CFCS0	AD2		
PA20	RF	NCS2/CFCS1	AD3		
PA21	RXD1	NCS6/CFCE2			
PA22	TXD1	NCS5/CFCE1			
PA23	SCK1	NWR1/NBS1/CFIOR			
PA24	RTS1	SDA10			
PA25	CTS1	SDCKE			
PA26	DCD1	NCS1/SDCS			
PA27	DTR1	SDWE			
PA28	DSR1	CAS			
PA29	RI1	RAS			
PA30	IRQ1	D30			
PA31	NPCS1	D31			

Figure 11-2. 144-ball LFBGA Package Drawing



All dimensions are in mm

12. Ordering Information

Table 12-1. Ordering Information

Ordering Code	MRL	Package	Package Type	Temperature Operating Range
AT91SAM7SE512B-AU	B	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE256B-AU	B	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE32B-AU	B	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE512B-CU	B	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE256B-CU	B	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE32B-CU	B	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE512-AU	A	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE256-AU	A	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE32-AU	A	LQFP128	Green	Industrial (-40· C to 85· C)
AT91SAM7SE512-CU	A	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE256-CU	A	LFBGA144	Green	Industrial (-40· C to 85· C)
AT91SAM7SE32-CU	A	LFBGA144	Green	Industrial (-40· C to 85· C)